

SID

Factory: Rot am See

Article:

575

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

17.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	150		2
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		3
B-RS-FR4-ML-0.20mm-070+070-TG150-HF	50200889	70	L2	4
		200		
		70	L3	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	260		5
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		6
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		7
B-RS-FR4-ML-0.20mm-070+070-TG150-HF	50200889	70	L4	8
		200		
		70	L5	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	260		9
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		10
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		11
B-RS-FR4-ML-0.20mm-070+070-TG150-HF	50200889	70	L6	12
		200		
		70	L7	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	150		13
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		14
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	15

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1910 µm

Version 1.2.14.15

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